





U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

101902317

1. Name of conveying party(ies):			2. Name and address of receiving party(ies):	
Sei TSUNODA, Hideharu NOBUTOKI and Noboru MIKAMI			Mitsubishi Denki Kabushiki Kaisha	
	11-23-01	Address:	2-3, Marunouchi 2-chome, Chiyoda-ku	
Additional name(s) of conveying party(ies) attached? \( \subseteq \text{Yes} \) \( \subseteq \text{No} \)			Tokyo 100-8310 JAPAN	
3. Nature of Conveyance:				
■ Assignment	er ge of Name			
Execution Date: October	20, 2001	Additiona	al name(s) and address(es) attached? □Yes ■No	
4. Application number(s) or patent number	er(s):	-		
If this document is being filed together wi	th a new application, the	execution da	ate of the application is:	
A. Patent Application No.(s)			B. Patent No.(s)	
09/941,766				
	Additional numbers attac	ched?	s ■No	
5. Name and address of party to whom correspondence concerning document should be mailed:		6. Total applications and patents involved: 1		
concerning document should be mailed:			7. Total fee (37 CFR 3.41): \$40.00	
			■ Enclosed	
22850		☐ Authorized to be charged to deposit account		
		8. Deposit	t account number: 15-0030 licate copy of this page if paying by deposit account)	
	DO NOT USE TI	HIS SPACE		
9. Statement and signature	•			
To the best of my knowledge and belief, copy of the original document.	the foregoing information	n is true and	correct and any attached copy is a true	
Norman F. Oblon	FOU	arther	11/2/11/	
Name of Person Signing	S	ignature	Date	
Registration Number: 24,618	Frederick D Registration (		stine	
	r of pages including this c			
	Do not detach th	is portion		
Mail documents to be recorded with requi	red cover sheet information	on to:		
•	Commissioner of Patent	s and Trade	emarks	
2:581 40.00 OP	Box Assign Washington, D			

	WHEREAS, I (WE) Sei Tsunoda, Hideharu Nobutoki and Noboru
TRT MALCE	Mikami, all residing at c/o MITSUBISHI DENKI KABUSHIKI
ERT NAMES D RESIDENCE DRESSES OF	KAISHA, 2-3, Marunouchi 2-chome, Chiyoda-ku,
E INVENTORS:	TOKYO 100-8310 JAPAN
BERT TITLE INVENTION:	LOW DIELECTRIC CONSTANT FILM  have invented certain new and useful improvements in: HAVING THERMAL RESISTANCE,  PROCESS FOR FORMING THE SAME, INSULATION FILM BETWEEN SEMICONDUCTOR  LAYERS USING THE SAME, AND SEMICONDUCTOR DEVICE
ERT DATE IN-	· · · · · · · · · · · · · · · · · · ·
CLARATION:	for which an application for Letters Patent was executed on October 20, 2001
	(Application No. 09/941, 766 , filed August 30, 2001 ), and
ERT NAME D ADDRESS OF MPANY OR HER ASSIGNEE:	WHEREAS, MITSUBISHI DENKI KABUSHIKI KAISHA
HER ASSIGNEE:	(hereinafter referred to as "ASSIGNEE") having a place of business at: 2-3, Marunouchi
	2-chome, Chiyoda-ku, TOKYO 100-8310 JAPAN
	is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;
	NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I (WE), by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions

and in any and all foreign countries and in and to any and all divisions, reissues, continua-

1/95

tions, substitutions and renewals thereof.

PATENT REEL: 012318 FRAME: 0280 I (WE) hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letter Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of Oblon, Spivak, McClelland, Maier & Neustadt, P.C. of Fourth Floor, 1755 Jefferson Davis Highway, Arlington, Virginia 22202 the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date:_	October	20,	2001	Sei Ssuroda
Date:_	October	20,	2001	(Signature of Inventor)  Aicle haru Modintohi (Signature of Inventor)
Date:_	October	20,	2001	Noboru Mi Hani (Signature of Inventor)
Date:_				(Signature of Inventor)
Date:_				(Signature of Inventor)
Date:_		<del></del>		(Signature of Inventor)
Date:_		<u> </u>		(Signature of Inventor)
Date: _				(Signature of Inventor)

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C. ATTORNEYS AT LAW

FOURTH FLOOR
1755 JEFFERSON DAVIS HIGHWAY
ARLINGTON, VIRGINIA 22202

1/95

RECORDED: 11/23/2001

PATENT REEL: 012318 FRAME: 0281